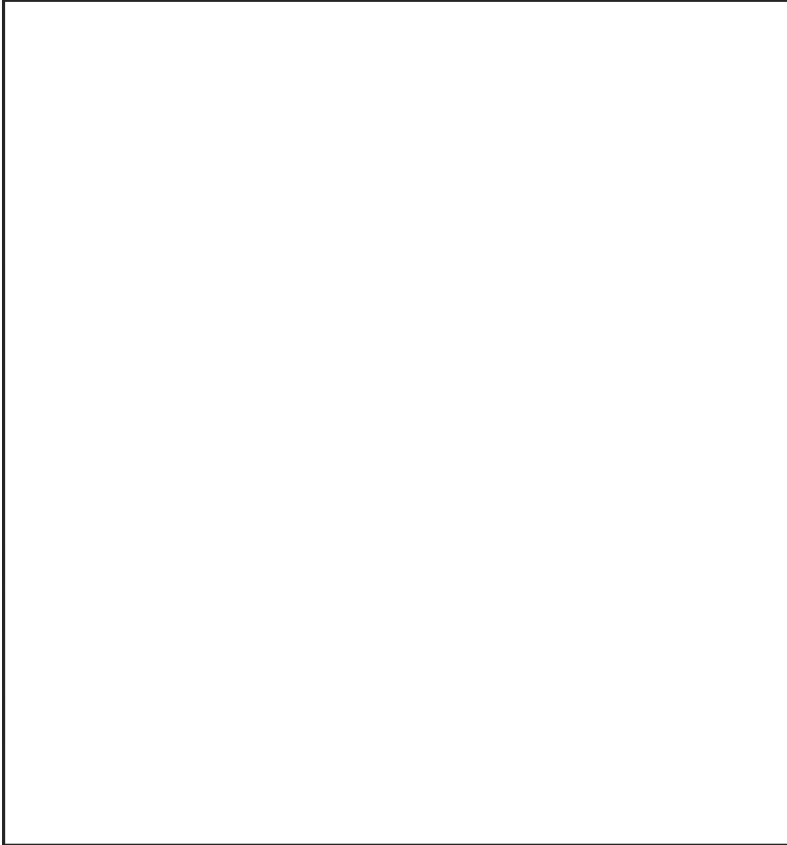


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01053	REV: E1	SVN REV: Not In VersionControl
	TID #: 01053		
PLOT NAME = Top Assembly Drawing	GENERATED : 3/30/2017	3:46:51 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01053	REV: E1	SVN REV: Not In VersionControl
	TID #: 01053		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 3/30/2017 3:46:52 PM		TEXAS INSTRUMENTS

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